



Material Content Data Sheet



Sales Product Name		BTS7006-1EPP		Issued		12. February 2019		
MA#		MA004962556						
Package		PG-TSDSO-14-22		Weight*		65.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.001	1.54	1.54	15376	15376
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		579	
	non noble metal	iron	7439-89-6	0.754	1.16		11583	
wire	non noble metal	copper	7440-50-8	30.617	47.04	48.27	470314	482621
	non noble metal	copper	7440-50-8	0.676	1.04	1.04	10389	10389
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.13		1345
	plastics	epoxy resin	-	3.416	5.25		52468	
		inorganic material	silicondioxide	60676-86-0	25.690	39.46	44.84	394631
leadfinish	non noble metal	tin	7440-31-5	1.642	2.52	2.52	25217	25217
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12536	12536
glue	plastics	epoxy resin	-	0.062	0.09		948	
		noble metal	silver	7440-22-4	0.291	0.45	0.54	4469
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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